

## Solution-Processed Hybrid Organic–Inorganic Complementary Thin-Film Transistor Inverter

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### Abstract

**Hybrid organic–inorganic complementary inverters composed of Dinaphtho [2,3-b:2',3'-f] thieno [3,2-b] thiophene (DNTT) and indium–gallium–zinc–oxide (IGZO) as p- and n- semiconductors, respectively, were fabricated. An IGZO film, used as an n-type semiconductor, was fabricated by a solution process. It showed a field-effect mobility of  $0.3 \text{ cm}^2 \cdot \text{V}^{-1} \cdot \text{s}^{-1}$ . The time and temperature required for the preparation of the IGZO were 5 min and  $200 \text{ }^\circ\text{C}$ , respectively. A hybrid complementary inverter was fabricated by combining the IGZO with a DNTT thin-film transistor.**

### 1. Introduction

Recently, oxide semiconductor materials such as amorphous indium–gallium–zinc oxide (a-IGZO) have attracted interest as an active layer of thin-film transistors (TFTs) owing to their high performance and low-temperature processing capability [1]. In particular, because a solution-processed IGZO can be prepared at low temperature, it can be applied to a printed circuit on a flexible plastic substrate. We have already carried out the development of an IGZO precursor ink for application in various printing processes [2,3]. However, the solution process requires a high annealing temperature and a long annealing time to completely eliminate the organic components in the precursor film [4]. In a previous study, we reported the fabrication of an a-IGZO TFT with a short annealing time using microwave. The a-IGZO TFT showed higher performance in spite of an annealing time of 5 min than annealing in an electric oven for 120 min [5]. Recently, some researchers have reported fabrication of IGZO TFTs prepared with a precursor at low temperature using both photo irradiation and conventional thermal annealing method [6,7]. In this case, the total process time was reduced compared with that using only the thermal annealing process. However, these processes requires pre- and/or post-thermal annealing processes of at least 1 h. Recently, we have reported that the annealing temperature and its processing time can be reduced by combining microwave annealing and photo irradiation using Xenon flash and Excimer lamps [8,9].

Organic TFTs have also been extensively studied as a semiconductor for high-performance TFTs because of the low process temperature and large area processability. Re-

cently, in a p-type organic semiconductor, the hole mobility has exceeded that of an amorphous silicon. Various electronic components such as inverters and logic circuits require both p- and n- type semiconductors. However, an n-type semiconductor a high electron mobility capable of being formed by a low-temperature process has not yet been reported. In the present study, we fabricated a hybrid organic–inorganic TFT complementary inverter.

### 2. Experimental

An IGZO precursor solution was prepared by dissolving Indium, Gallium, and Zinc nitrates in an alcohol. The resulting precursor was filtrated using a membrane filter. The inverter was fabricated in a top-contact and bottom-gate configuration. Dinaphtho [2,3-b:2',3'-f] thieno [3,2-b] thiophene (DNTT) and IGZO films were used as a p- and n-type semiconductors, respectively. The IGZO precursor film was fabricated on the surface of a thermally grown 300-nm-thick silicon dioxide layer on a silicon wafer by spin coating at 2000 rpm for 30 s. The precursor films were annealed in a single-mode microwave cavity at  $200 \text{ }^\circ\text{C}$  for 5 min at a frequency of 2.45 GHz. The temperature was measured using a radiation thermometer (FTK9, Japan Sensor). A 30-nm layer of DNTT was deposited through a shadow mask using thermal evaporation. Source and drain electrodes made of Au for the p-channel and Al for the n-channel were deposited onto each sample.

### 2. Results

The transfer characteristics of both n- and p-channel transistors are shown in Figs. 1 and 2. The IGZO TFT shows a field effect mobility of  $0.3 \text{ cm}^2 \cdot \text{V}^{-1} \cdot \text{s}^{-1}$ . Although the IGZO TFT was fabricated by a solution process at  $200 \text{ }^\circ\text{C}$  for 5 min, the mobility shows a relatively high performance compared with the other n-type TFTs prepared by the solution process at low temperature [10]. The transfer characteristics of the DNTT TFT exhibits field effect mobility of  $1 \text{ cm}^2 \cdot \text{V}^{-1} \cdot \text{s}^{-1}$ .

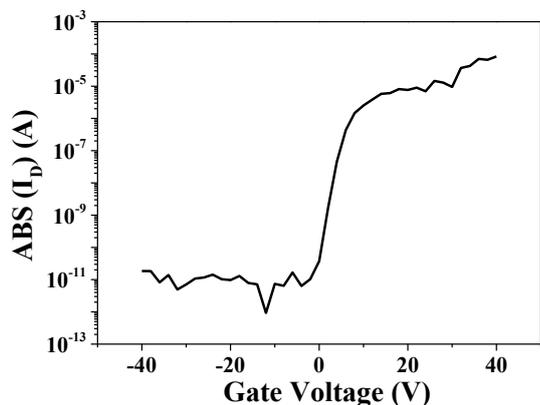


Fig. 1 Transfer characteristics of TFTs fabricated with solution-processed IGZO by annealing an IGZO precursor solution using microwave at 200 °C for 5 min.

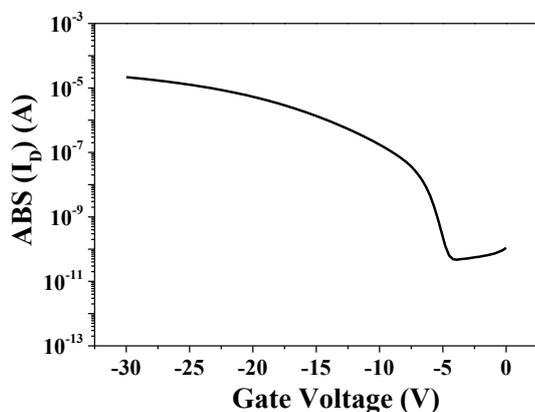


Fig. 2. Transfer characteristics of the TFTs fabricated with DNNT as a p-type organic semiconductor.

Then, hybrid complementary inverters were developed using these organic (i.e., p-type) and inorganic (i.e., n-type), TFTs to confirm the inverter operation when the IZGO prepared by the solution process at low temperature was used as an n-type channel. The voltage transfer characteristics and maximum dc voltage gain at supply voltage of  $V_{DD} = 5, 10, 20,$  and  $30$  V are shown in Fig. 3. The inverter operation of the device was observed, and the maximum gain values at  $V_{DD} = 20$  and  $30$  V were  $55$  V/V and  $58$  V/V, respectively. These results revealed that the IGZO prepared by the solution process at low temperature can be used as an n-type channel of an inverter circuit.

### 3. Conclusions

We have fabricated a hybrid organic–inorganic complementary TFT inverter using a solution-processed IGZO TFT as an n-channel. Although the TFT was fabricated at low temperature (200 °C) and in a short time (5 min), it showed good mobility, and the CMOS that used the IGZO as an n-channel exhibited an inverter operation.

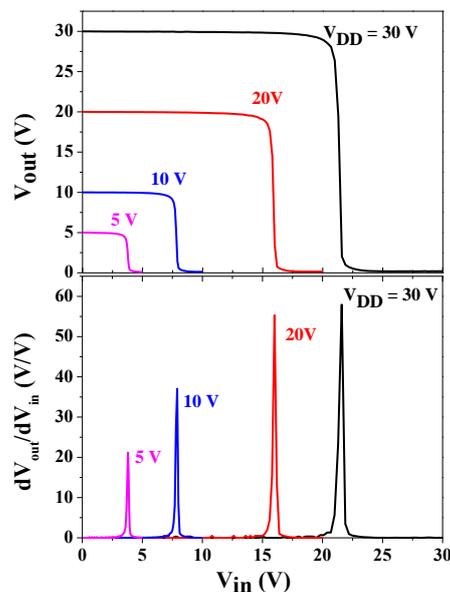


Fig. 3 Voltage transfer characteristics and the corresponding dc gain value of the inverter.

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